

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: Isao OCHIAI

Group Art Unit: 2827

Serial No. 10/772,345

Examiner: Robert B. Davis

Filed: February 6, 2004

Attorney Docket No. 2905-107

Customer Number: 52190

For: **LEAD FRAME, RESIN SEALING MOLD AND METHOD FOR  
MANUFACTURING A SEMICONDUCTOR DEVICE USING THE SAME**

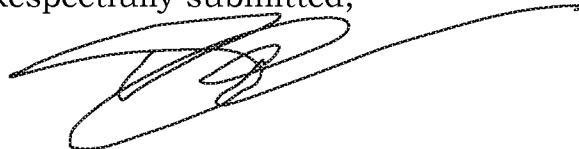
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**REQUEST FOR APPROVAL OF DRAWING CHANGES**

Dear Sir:

Attached hereto are substitute FIGS. 16-18 in which the figures are labeled as prior art in accordance with the Examiner's requirement. No new matter has been added. Approval and entry of such new drawings are respectfully requested. In the event that any fees are due in connection with this filing, please charge or credit our Deposit Account No. 14-1437.

Respectfully submitted,



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